



Final Product Change Notification

201710001F01

Issue Date: 10-Jan-2018
Effective Date: 22-Apr-2018

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Management Summary

Cu Wire is being added as a wirebond material option for LPC31xxFET180 and LPC32xxFET296 in TFBGA180 and TFBGA296 package at assembly site NXP-ATKH.

Change Category

<input type="checkbox"/> Wafer Fab Process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Test Location	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Process	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Electrical spec./Test coverage

LPC31xxFET180,
LPC32xxFET296 Cu Wire
Qualification for NXP-ATKH

Details of this Change

Copper wire has been qualified and will be added as a wirebond material. To support a robust wirebond process the mold compound has also changed. Upon expiration of this notice, NXP will begin shipping product with copper wire.

See attached Self Qualification Report (SQR) for details of the affected part numbers, material changes and qualification test results.

Why do we Implement this Change

Adding Copper wire is required to mitigate against raw material cost increases and for supply assurance. The die attach material, and mold compound change enable a robust Cu wirebond process.

Identification of Affected Products

Top side marking

Product revision is incremented. See marking details in attached SQR document.

Product Availability

Sample Information

Samples are available from 01-Jan-2018

Only samples of LPC3141FET180 and LPC3250FET296 will be available.

Samples with Cu wire can be ordered under the following part numbers:

LPC3141FET180/CP3359

LPC3250FET296/CP3360

Production

Planned first shipment 22-Apr-2018

Impact

Wire composition, lead frame finish and mold compound are the only change to form. No Impact to fit or function. Reliability is equivalent or improved.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 09-Feb-2018.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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Position Senior Quality Engineer
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Changed Orderable Part#	Changed Part 12NC	Changed Part Number	Changed Part Description	Package Outline	Package Name	Status	Product Line
LPC3220FET296/01,5	935290763551	LPC3220FET296/01	32-BIT ARM9	SOT1048-1	TFBGA296	RFS	BL Microcontrollers
LPC3250FET296/01,5	935290766551	LPC3250FET296/01	32-BIT ARM9	SOT1048-1	TFBGA296	RFS	BL Microcontrollers
LPC3131FET180,551	935288014551	LPC3131FET180	32-bit ARM	SOT570-3	TFBGA180	RFS	BL Microcontrollers
LPC3240FET296/01,5	935290765551	LPC3240FET296/01	32-BIT ARM9	SOT1048-1	TFBGA296	RFS	BL Microcontrollers